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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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HD74HC563/HD74HC573

Octal Transparent Latches (with 3-state outputs)



ADE-205-509 (Z)
1st. Edition
Sep. 2000

Description

When the latch enable (LE) input is high, the Q outputs of HD74HC563 will follow the inversion of the D inputs and the Q outputs of HD74HC573 will follow the D inputs. When the latch enable goes low, data at the D inputs will be retained at the outputs until latch enable returns high again. When a high logic level is applied to the output control input, all outputs go to a high impedance state, regardless of what signals are present at the other inputs and the state of the storage elements.

Features

- High Speed Operation: t_{pd} (Data to Q, $\overline{Q}$) = 11 ns typ ($C_L = 50$ pF)
- High Output Current: Fanout of 15 LSTTL Loads
- Wide Operating Voltage: $V_{CC} = 2$ to 6 V
- Low Input Current: 1 μ A max
- Low Quiescent Supply Current: I_{CC} (static) = 4 μ A max ($T_a = 25^\circ\text{C}$)

Function Table

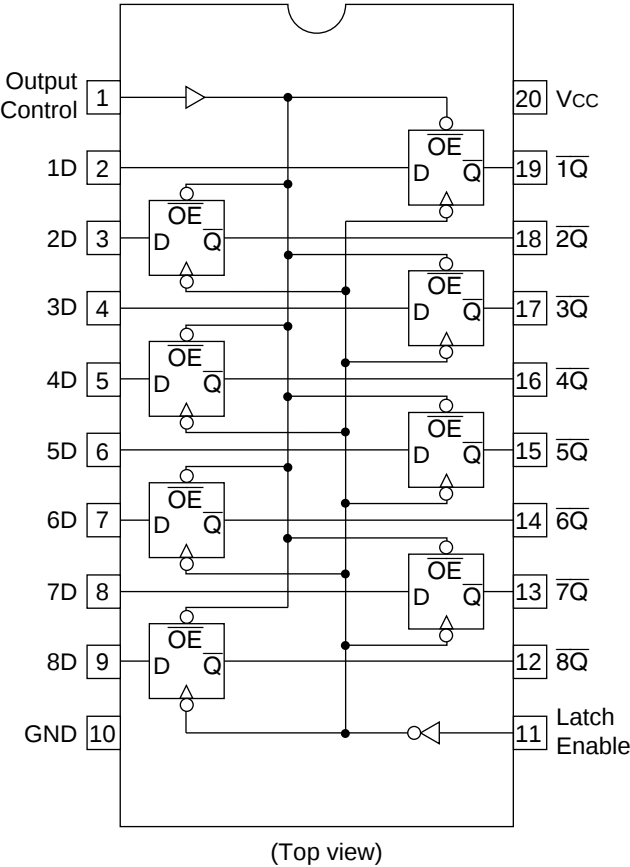
Output Control	Latch Enable	Data	Outputs	
			HD74HC563	HD74HD573
L	H	H	L	H
L	H	L	H	L
L	L	X	$\overline{Q_0}$	Q_0
H	X	X	Z	Z

$\overline{Q_0}$: level of Q before the indicated Steady-state input conditions were established.

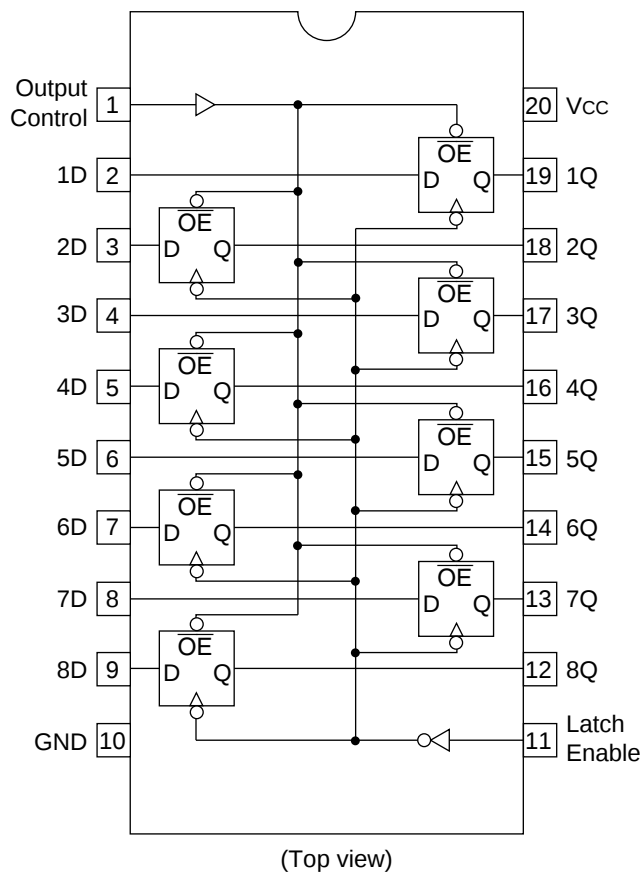
Q_0 : complement of $\overline{Q_0}$ or level of $\overline{Q}$ before the indicated Steady-state input conditions were established.

Pin Arrangement

HD74HC563



HD74HC573

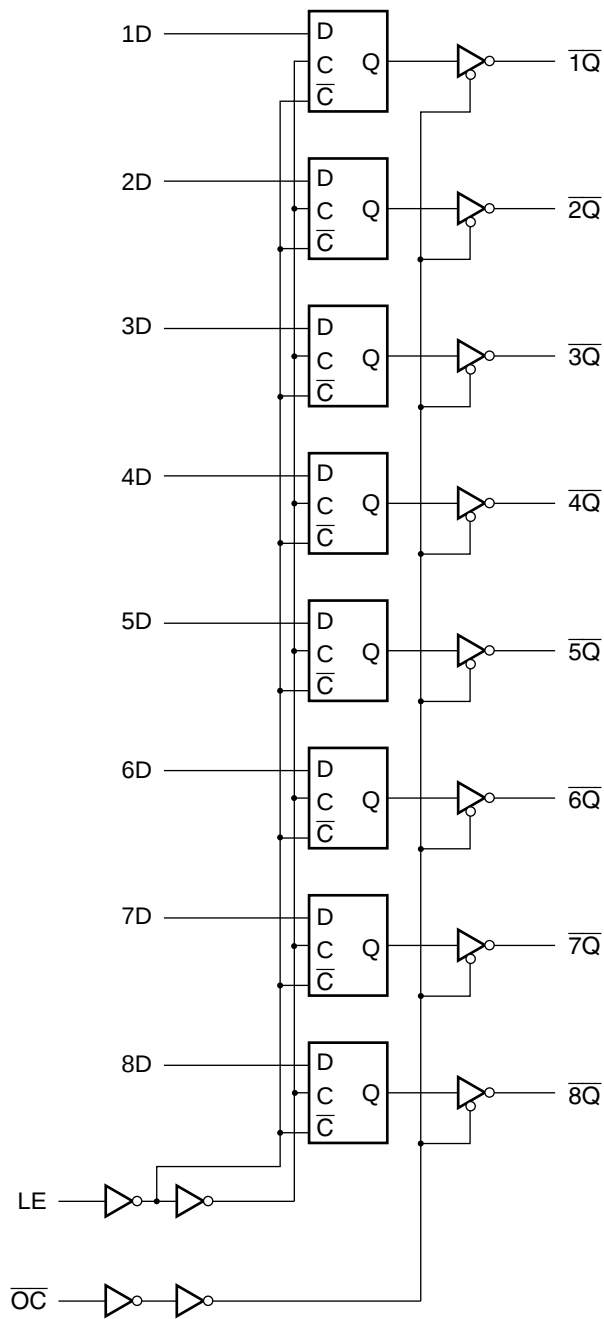


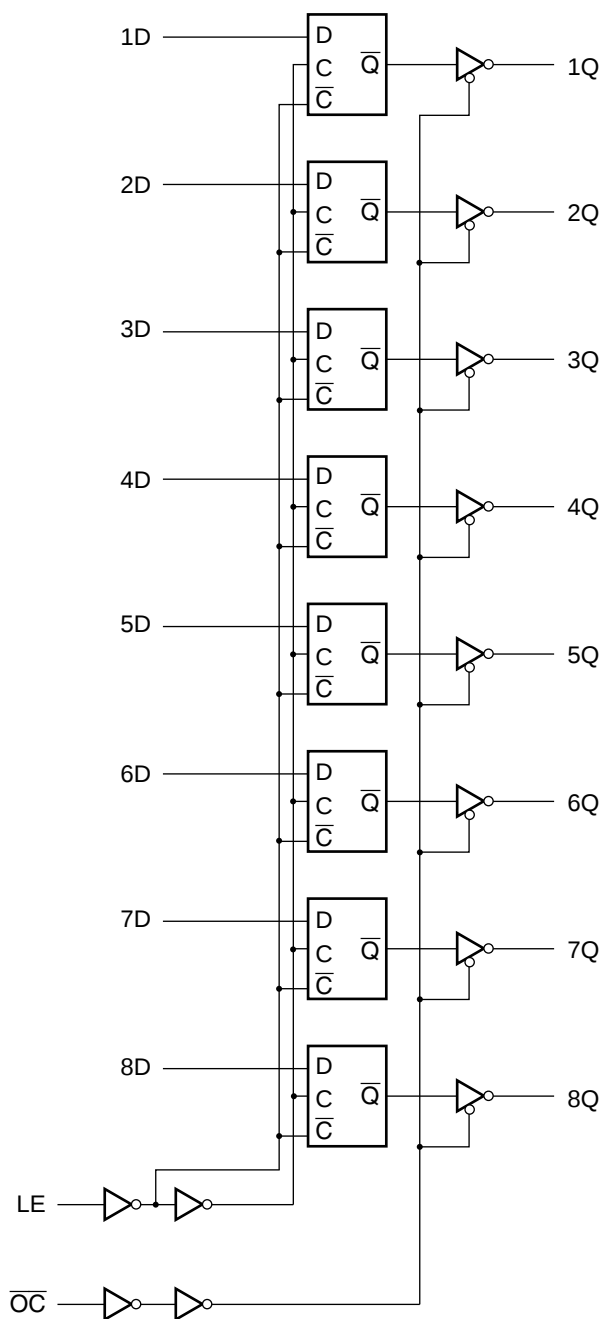
Absolute Maximum Ratings

Item	Symbol	Rating	Unit
Supply voltage range	V_{CC}	-0.5 to +7.0	V
Input voltage	V_{IN}	-0.5 to $V_{CC} + 0.5$	V
Output voltage	V_{OUT}	-0.5 to $V_{CC} + 0.5$	V
Output current	I_{OUT}	± 35	mA
DC current drain per V_{CC} , GND	I_{CC} , I_{GND}	± 75	mA
DC input diode current	I_{IK}	± 20	mA
DC output diode current	I_{OK}	± 20	mA
Power Dissipation per package	P_T	500	mW
Storage temperature	T_{stg}	-65 to +150	$^{\circ}\text{C}$

Block Diagram

HD74HC563





DC Characteristics

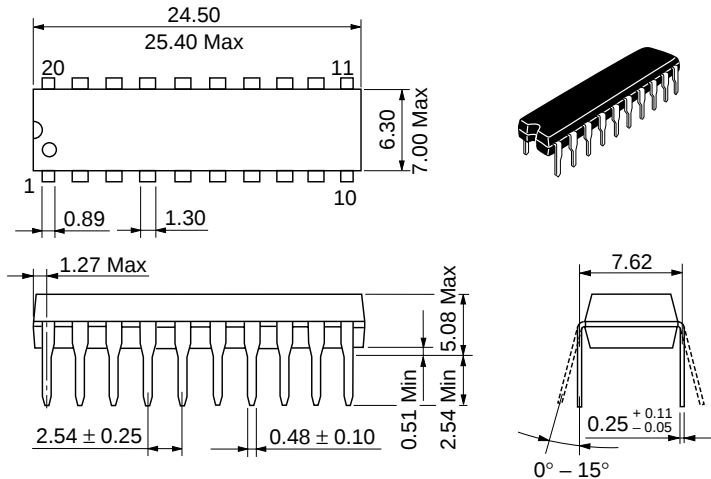
Item	Symbol	V _{CC} (V)	Ta = 25°C			Ta = -40 to +85°C		Unit	Test Conditions	
			Min	Typ	Max	Min	Max			
Input voltage	V _{IH}	2.0	1.5	—	—	1.5	—	V		
		4.5	3.15	—	—	3.15	—			
		6.0	4.2	—	—	4.2	—			
	V _{IL}	2.0	—	—	0.5	—	0.5	V		
		4.5	—	—	1.35	—	1.35			
		6.0	—	—	1.8	—	1.8			
Output voltage	V _{OH}	2.0	1.9	2.0	—	1.9	—	V	Vin = V _{IH} or V _{IL} I _{OH} = -20 μA	
		4.5	4.4	4.5	—	4.4	—			
		6.0	5.9	6.0	—	5.9	—			
		4.5	4.18	—	—	4.13	—			I _{OH} = -6 mA
		6.0	5.68	—	—	5.63	—			I _{OH} = -7.8 mA
	V _{OL}	2.0	—	0.0	0.1	—	0.1	V	Vin = V _{IH} or V _{IL} I _{OL} = 20 μA	
		4.5	—	0.0	0.1	—	0.1			
		6.0	—	0.0	0.1	—	0.1			
		4.5	—	—	0.26	—	0.33			I _{OL} = 6 mA
		6.0	—	—	0.26	—	0.33			I _{OL} = 7.8 mA
Off-state output current	I _{OZ}	6.0	—	—	±0.5	—	±5.0	μA	Vin = V _{IH} or V _{IL} , Vout = V _{CC} or GND	
Input current	I _{in}	6.0	—	—	±0.1	—	±1.0	μA	Vin = V _{CC} or GND	
Quiescent supply current	I _{CC}	6.0	—	—	4.0	—	40	μA	Vin = V _{CC} or GND, Iout = 0 μA	

AC Characteristics ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6 \text{ ns}$)

Item	Symbol	$V_{CC} \text{ (V)}$	$T_a = 25^\circ\text{C}$			$T_a = -40 \text{ to } +85^\circ\text{C}$		Unit	Test Conditions
			Min	Typ	Max	Min	Max		
Propagation delay time	t_{PLH}	2.0	—	—	110	—	140	ns	Data to $\overline{Q}$
	t_{PHL}	4.5	—	11	22	—	28		
		6.0	—	—	19	—	24		
	t_{PLH}	2.0	—	—	115	—	145	ns	Clock to $\overline{Q}$
	t_{PHL}	4.5	—	13	23	—	29		
		6.0	—	—	20	—	25		
Output enable time	t_{ZH}	2.0	—	—	150	—	190	ns	
	t_{ZL}	4.5	—	14	30	—	38		
		6.0	—	—	26	—	33		
Output disable time	t_{HZ}	2.0	—	—	150	—	190	ns	
	t_{LZ}	4.5	—	15	30	—	38		
		6.0	—	—	26	—	33		
Setup time	t_{su}	2.0	75	—	—	90	—	ns	
		4.5	15	2	—	19	—		
		6.0	13	—	—	16	—		
Hold time	t_h	2.0	5	—	—	5	—	ns	
		4.5	5	-1	—	5	—		
		6.0	5	—	—	5	—		
Pulse width	t_w	2.0	80	—	—	100	—	ns	
		4.5	16	4	—	20	—		
		6.0	14	—	—	17	—		
Output rise/fall time	t_{TLH}	2.0	—	—	60	—	75	ns	
	t_{THL}	4.5	—	4	12	—	15		
		6.0	—	—	10	—	13		
Input capacitance	C_{in}	—	—	5	10	—	10	pF	

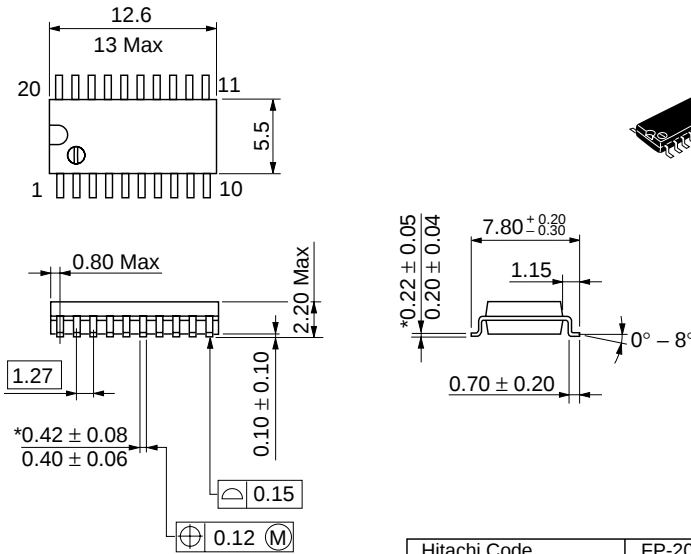
Package Dimensions

Unit: mm



Hitachi Code	DP-20N
JEDEC	—
EIAJ	Conforms
Mass (reference value)	1.26 g

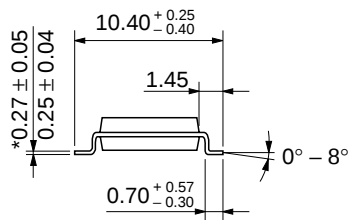
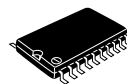
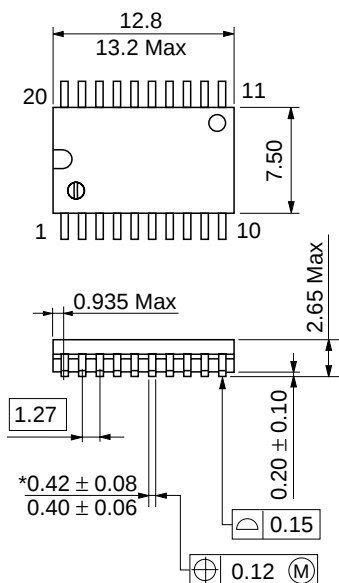
Unit: mm



Hitachi Code	FP-20DA
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.31 g

*Dimension including the plating thickness
Base material dimension

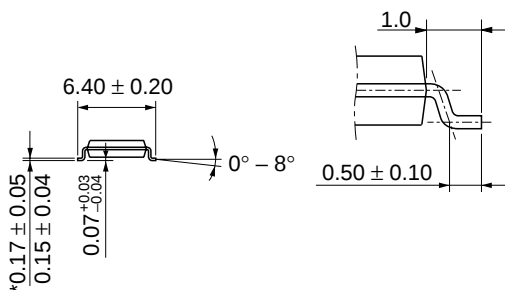
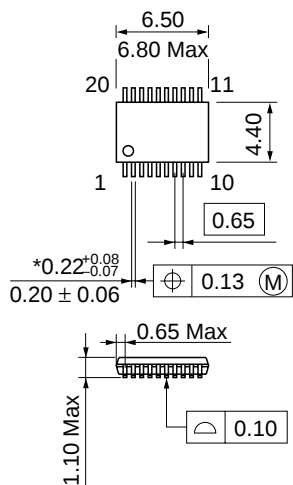
Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-20DB
JEDEC	Conforms
EIAJ	—
Mass (reference value)	0.52 g

Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	TTP-20DA
JEDEC	—
EIAJ	—
Mass (reference value)	0.07 g

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